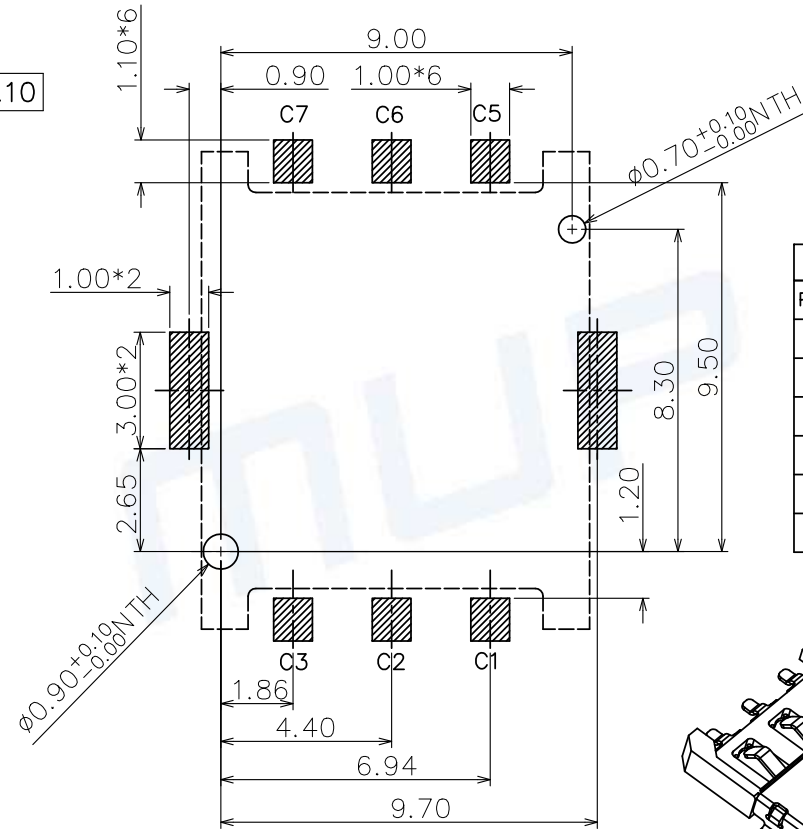
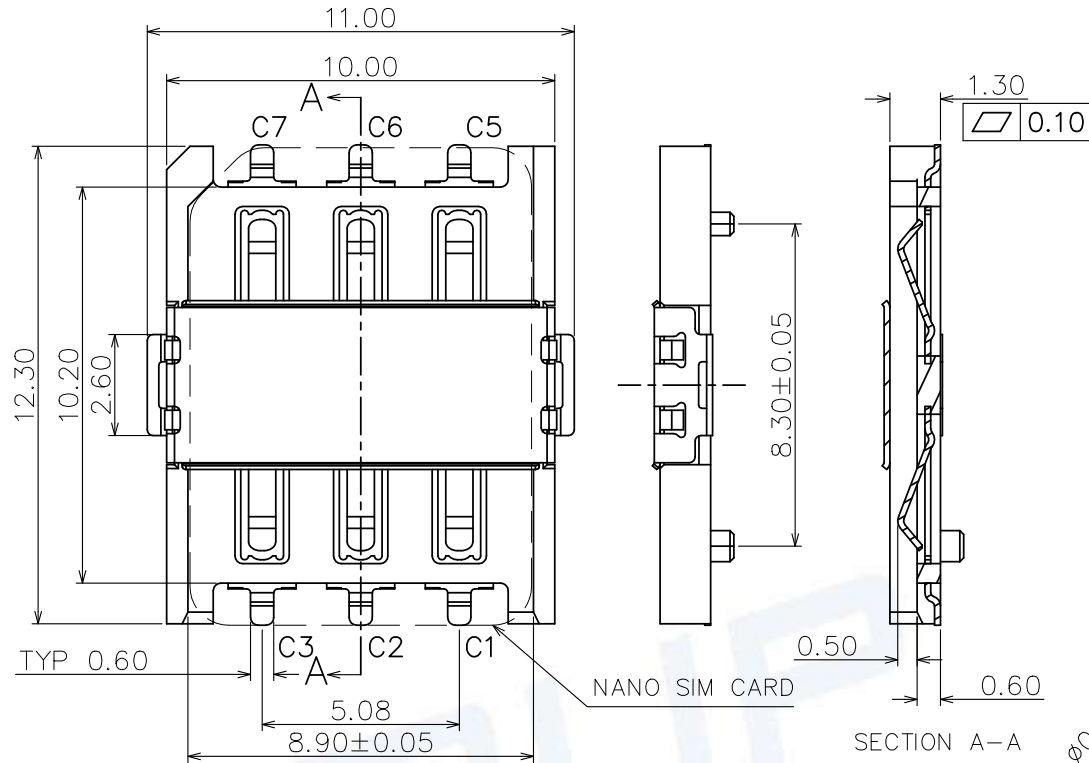
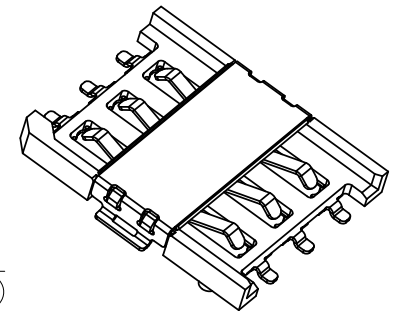


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Henry Apr.09.2014
X2					



Nano-SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



RECOMMENDED P.C.B LAYOUT  
COMPONENT SIDE(TOLERANCE ±0.05)

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
3	SHELL	1	Stainless Steel	SMT area:Gold plated

Unless otherwise specified, other tolerance are:

**MUP** MUP INDUSTRIAL CO.,LTD.

NAME: **Nano-SIM Card Connector**

MODEL NO: **MUP-C781-2**

TYPE: **H1.50mm 6 PIN**

PROJ.	UNIT	SCALE	DRAWN	Henry Apr.09.2014	DWG NO.:
	mm	1:1	CHECKED	Henry Apr.09.2014	DWG-MUP-C781-2
CUSTOMER DRAWING			APPROVAL	Simon Apr.09.2014	SHEET
					REVISION
					1/1
					X1

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 12.30LX10.00WX1.50H mm

Weight: Approx 0.53±0.2g

Durability: 1,500 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max

Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vaporphase: 215°C, 30sec.Max

IR reflow: 250°C, 5sec.Max

Manual soldering: 370°C, 3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C

Operating humidity: 10%~+95%RH

